Features：

- **n** Isolated mounting base 3000V~
- **n** Solder joint technology with increased power cycling capability
- **n** Space and weight saving

Typical Applications

- **n** Various rectifiers
- **n** DC supply for PWM inverter

V_{RRM}	Type & Outline
800V	MDC110-08-224H3
1000V	MDC110-10-224H3
1200V	MDC110-12-224H3
1400V	MDC110-14-224H3
1600V	MDC110-16-224H3
1800V	MDC110-18-224H3

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	T_j(°C)	VALUE			UNIT
				Min	Type	Max	
$I_{F(AV)}$	Mean forward current	180° half sine wave 50Hz Single side cooled, T_C=100°C	150			110	A
$I_{F(RMS)}$	RMS forward current					173	A
I_{RRM}	Repetitive peak current	at V_{RRM}	150			8	mA
I_{FSM}	Surge forward current	V_R=60%V_{RRM},,t=10ms half sine,	150			2.0	kA
I^2t	I^2t for fusing coordination					20.0	10^3A^2s
V_{FO}	Threshold voltage		150			0.80	V
r_F	Forward slope resistance					1.74	mΩ
V_{FM}	Peak forward voltage	I_{FM}=330A	25			1.55	V
$R_{th(j-c)}$	Thermal resistance Junction to case	At 180^0 sine. Single side cooled per chip				0.35	°C/W
$R_{th(c-h)}$	Thermal resistance case to heatsink	At 180^0 sine. Single side cooled per chip				0.20	°C/W
V_{iso}	Isolation voltage	50Hz,R.M.S,t=1min,I_{iso}:1mA(MAX)		3000			V
F_m	Terminal connection torque(M5)			2.5		4	N·m
	Mounting torque(M6)			4.5		6	N·m
T_{vj}	Junction temperature			-40		150	°C
T_{stg}	Stored temperature			-40		125	°C
W_t	Weight				100		g
Outline	224H3						

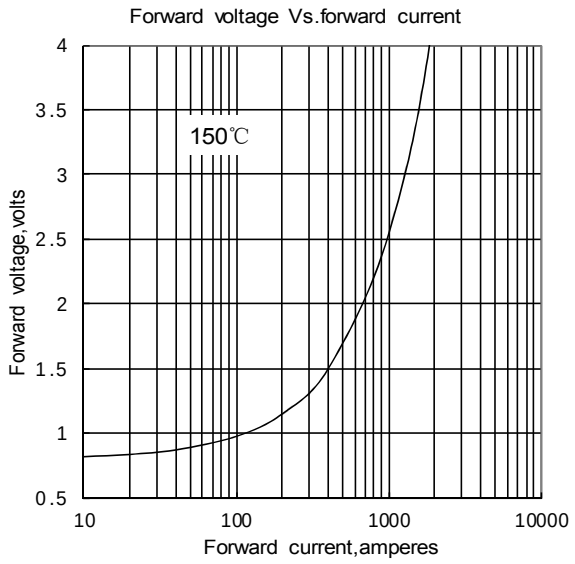


Fig1

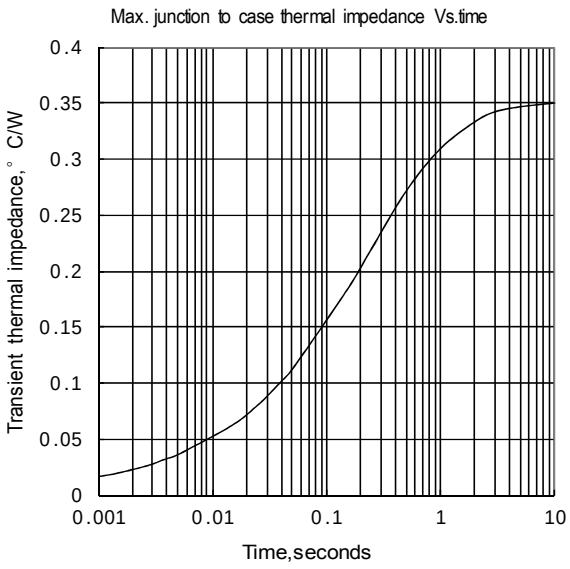


Fig2

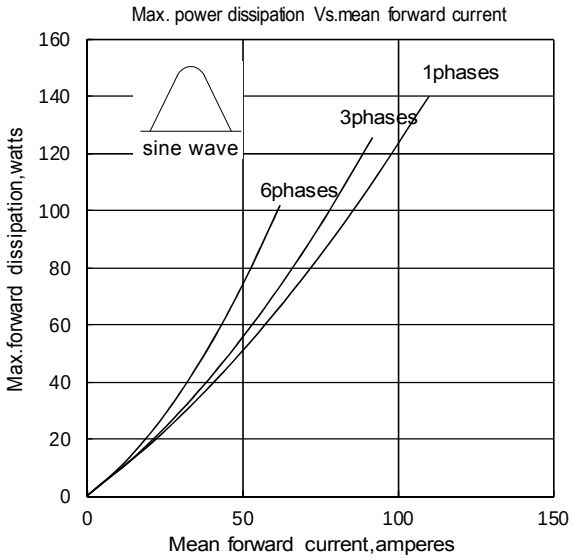


Fig3

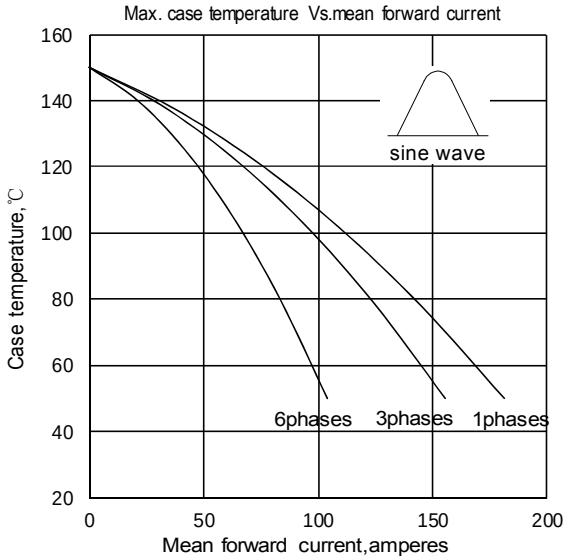


Fig4

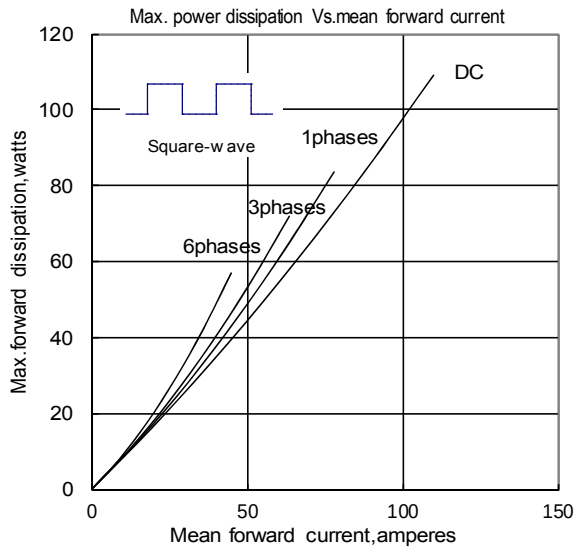


Fig5

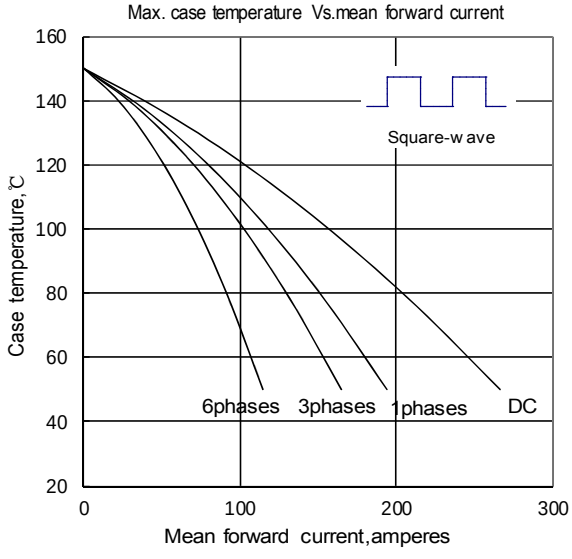


Fig6

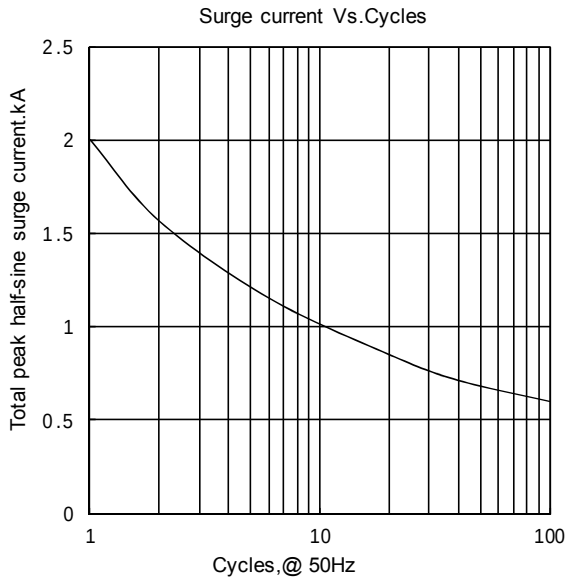


Fig.7

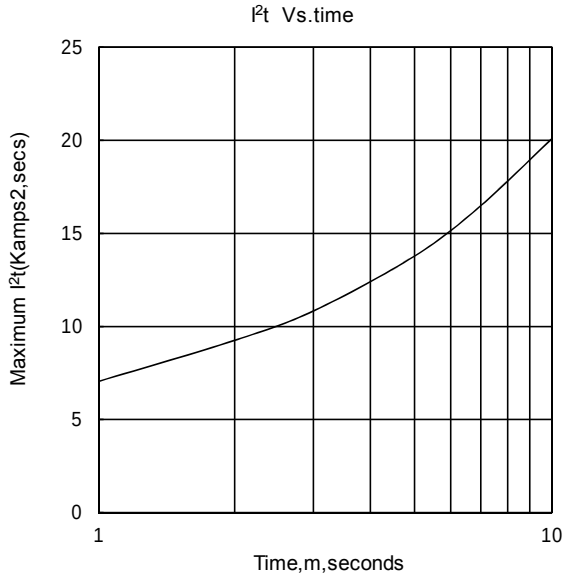
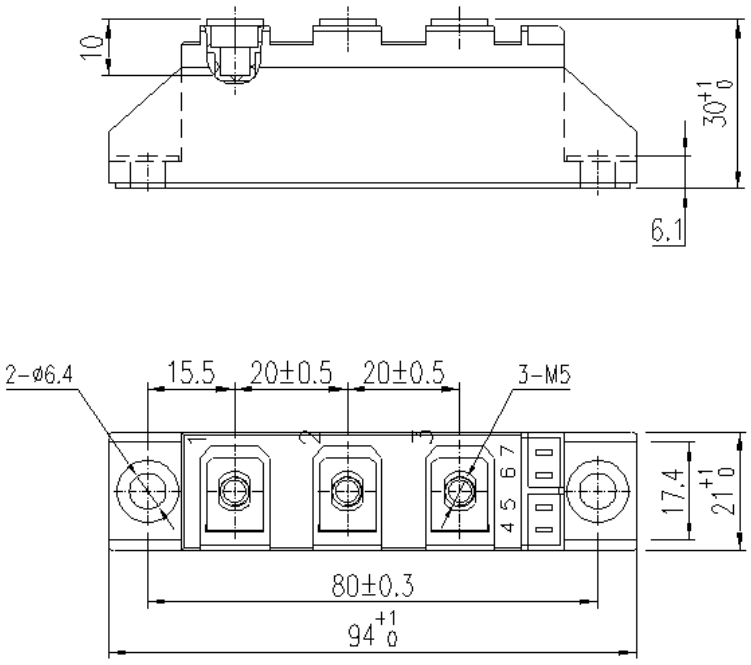
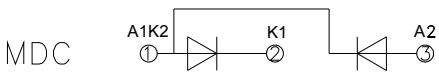


Fig.8

Outline:





Unmarked dimensional tolerance：±0.5mm

TECHSEM reserves the right to change specifications without notice.